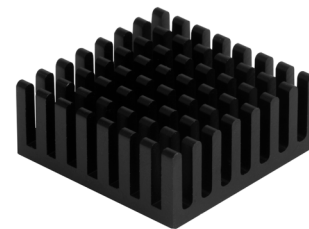




MODEL: HSB24-252510 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- small footprint
- top mount
- aluminum alloy



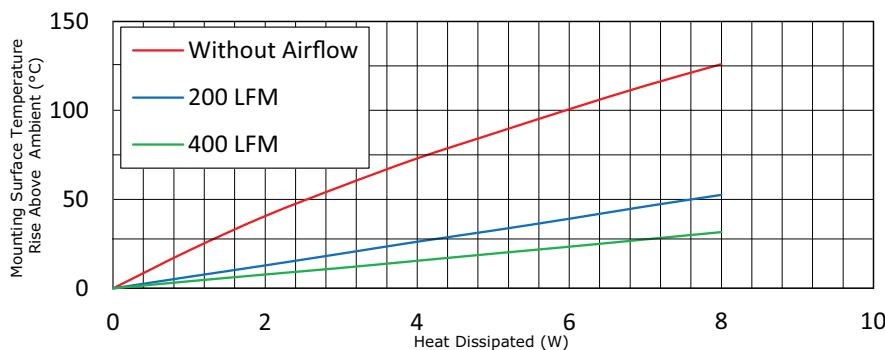
MODEL

| HSB24-252510 | thermal resistance ¹ | | | power dissipation ¹ @ 75°C ΔT, nat conv [W] |
|--------------|---------------------------------|------------------------|-----------------------|---|
| | @ 75°C ΔT, nat conv [°C/W] | @ 1 W, nat conv [°C/W] | @ 1 W, 200 LFM [°C/W] | |
| | 18.10 | 21.3 | 6.5 | 4.0 |

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

| Power [W] | Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C] | | |
|-----------|---|---------|---------|
| | Natural Conv. | 200 LFM | 400 LFM |
| 0 | 0 | 0 | 0 |
| 1 | 21.3 | 6.5 | 4.0 |
| 2 | 40.6 | 12.9 | 7.8 |
| 3 | 57.3 | 19.5 | 11.5 |
| 4 | 73.0 | 26.2 | 15.5 |
| 5 | 86.9 | 32.5 | 19.5 |
| 6 | 100.6 | 39.1 | 23.4 |
| 7 | 113.8 | 46.0 | 27.5 |
| 8 | 125.9 | 52.5 | 31.6 |



T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ± 0.5 mm

| | |
|----------|----------------|
| MATERIAL | AL 6063-T5 |
| FINISH | black anodized |
| WEIGHT | 8.8 g |

